Technical Data Sheet Of

Section I:

Product Description

The lead-free and leaded alloy solder wire are made by sophisticated and advanced wire drawing equipment, with characteristics of fast wetting, low spatter, low level of fumes, clear non-tacky residue, and No-Clean. They are widely used in various manual soldering and robotic automatic solder.

Section II:

Product Information

Alloy Model Lead-Free and Leaded Flux Type Rosin Cored

Alloy Model	ROL0 (HY208)	ROL1 (HY201)	Melting Point °C	Flux Type	Flux %	Wire Diam (mm)	WT Per Roll	Residue
SAC305	√	√	217/221	Rosin	1.8% 2.2% 2.5% 3.3%	0.5/0.6/0.8/1.0/1.2/ 1.5/2.0/2.5/3.0/3.2	50g 100g 500g 750g 800g 900g 1000g	No-Clean
SAC0307	√	√	217/228					
Sn99Cu0.7	√	√	227					
Sn99Cu0.7Ni	√	√	227					
Sn97Cu3	√	√	227/300					
Sn63Pb37	√	√	183					
Sn60Pb40	√	√	183/190					

Chemical Properties			
TEST	ROL0 (HY208)	ROL1 (HY201)	Test Method
Halide Content	<0.05% Pass	<0.5% Pass	IPC-J-STD-004A/B
Copper Plate Corrosion Test	Pass	Pass	IPC-TM-650
Coper Mirror Test	Pass	Pass	IPC-TM-650

Electrical Properties			
TEST	ROL0 (HY208)	ROL1 (HY201)	Test Method
Surface insulation Resistance Test	Pass	Pass	IPC-J-STD-004A/B
Electrochemical Migration Test	Pass	Pass	IPC-J-STD-004A/B
Bell core SIR Test	Pass	Pass	GR-78-CORE
Bell core EM Test	Pass	Pass	GR-78-CORE

Section III:

Product Features

- Fast Wetting: Good Rosin Activity, Easy To Tin, Excellent Thermal Conductivity
- Low Flux Spatter: Safer to Use, Cleaner Working Environment
- Low Levels of Fumes: User Friendly, Cleaner Working Environment
- Clear, low residue: No-Clean, Easy Using
- Good & Bright Joint: Enough Tin Alloy Content, Not Blacken, Nice Appearance
- Halogen/Halide-Free: Environmental-Friendly and High Electrical Reliability

Section IV:

Product Application

The lead-free and leaded alloy solder wire are widely used in Electronics fields, such as:

- PCBs
- Led Lighting
- TV/Video/DVD
- Audio Equipments
- Mobiles Repair
- Computer
- Home Appliances
- Instruments
- Transformers etc...

Section V:

Cleaning The flux residue is non-corrosive and non-conductive under normal conditions of use.

It is No-Clean after Soldering

Section VI:

Storage and Shelf-Life Storage in a dry, non-corrosive environment between 10-40℃. Flux-cored solder wire has a shelf life determined by the alloy used in the wire. For alloys containing more than 70% lead, the shelf life is 2 years from the date of manufacture. Other alloys have a shelf life 3 years from the date of manufacture if storage well